4.5 Ω High Bandwidth, Dual **SPDT Analog Switch**

The NLAS4717 is an advanced CMOS analog switch fabricated in sub-micron silicon gate CMOS technology. The device is a dual independent Single Pole Double Throw (SPDT) switch featuring two low $R_{DS(on)}$ of 4.5 Ω at 3.0 V.

The device also features guaranteed Break-Before-Make (BBM) switching, assuring the switches never short the driver.

The NLAS4717 is available in two small size packages:

• Micro10: $3.0 \times 5.0 \text{ mm}$ ♦ Flip-Chip-10: 2.0 x 1.5 mm

Features

- Low $R_{DS(on)}$: 4.5 Ω @ 3.0 V
- Matching Between the Switches $\pm 0.5 \Omega$
- Wide Low Voltage Range: 1.8 V to 5.5 V
- High Bandwidth > 40 MHz
- 1.65 V to 5.5 V Operating Range
- Low Threshold Voltages on Pins 4 and 8 (CTRL Pins)
- Ultra-Low Charge Injection ≤ 6.0 pC
- Low Standby Current $I_{CC} = 1.0 \text{ nA (Max)} @ T_A = 25^{\circ}C$
- LEASE CONTACT • OVT* on Pins 4 and 8 (CTRL Logic Pins)
- Pb-Free Packages are Available

Typical Applications

- Cell Phones
- PDAs
- MP3s
- Digital Still Cameras

Important Information

- ESD Protection:
 - HBM = 2000 V, MM = 200 V
- Latchup Max Rating: 200 mA (Per JEDEC EIA/JESD78)
- Pin-to-Pin Compatible with MAX4717

*OVT

• Overvoltage Tolerance (OVT) specific pins to operate higher than normal supply voltages, with no damage to the devices or to signal integrity.



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MARKING DIAGRAMS











= Assembly Location

= Work Week = Pb-Free Package

FUNCTION TABLE

IN_	NO_	NC_
0	OFF	ON
1	ON	OFF

ORDERING INFORMATION

Device	Package	Shipping [†]
NLAS4717FCT1	Flip-Chip-10	3000 / Tape & Reel
NLAS4717FCT1G	Flip-Chip-10 (Pb-Free)	3000 / Tape & Reel
NLAS4717MR2	Micro10	4000 / Tape & Reel
NLAS4717MR2G	Micro10 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications. including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

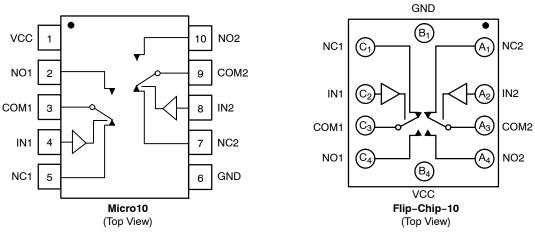


Figure 1. Device Circuit Diagrams and Pin Configurations

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V+	Positive DC Supply Voltage	-0.5 to $+7.0$	٧
V _{IS}	Analog Input Voltage (V _{NO} , V _{NC} , or V _{COM}) (Note 1)	$-0.5 \le V_{IS} \le V_{CC} + 0.5$	٧
V _{IN}	Digital Select Input Voltage	$-0.5 \le V_{I} \le +7.0$	V
I _{IK}	DC Current, Into or Out of Any Pin (Continuous)	±100	mA
I _{PK}	Peak Current (10% Duty Cycle)	±200	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V+	DC Supply Voltage	1.8	5.5	V
V _{IN}	Digital Select Input Voltage	GND	5.5	V
V _{IS}	Analog Input Voltage (NC, NO, COM)	GND	V _{CC}	V
T _A	Operating Temperature Range	-40	+85	°C
t _r , t _f		3.3 V ± 0.3 V 5.0 V ± 0.5 V 0	100 20	ns/V

ANALOG SWITCH DC CHARACTERISTICS

				-40°C 1	to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Max	Unit
V _{IH}	Input Logic High Voltage	V _{OUT} = 0.1 V	1.65 to 2.2	V _{CC} x 0.55	-	V
		I _{OUT} ≤ 20 μA	2.7 to 3.6	V _{CC} x 0.5	-	
			4.5 to 5.5	2.0	-	
V _{IL}	Input Logic Low Voltage	V _{OUT} = -V _{CC} - 0.1 V	1.65 to 2.2	_	V _{CC} x 0.2	V
		I _{OUT} ≤ 20 μA	2.7 to 3.6	_	V _{CC} x 0.2	
			4.5 to 5.5	_	0.8	
I _{IN}	Input Leakage Current	V _{IN} – V _{CC} or GND	5.0	-100	+100	nA
V _{CC}	Power Supply Range	All	-	1.65	5.5	V
I _{CC}	Supply Current	V _{IN} = V _{CC} or GND	1.8	-	1.0	μΑ
		I _{OUT} = 0 μA	3.3	_	1.0	
			5.0	-	1.0	
V _{IS}	Analog Signal Range	Key parameter	-	0	V _{CC}	V

Signal voltage on NC, NO, and COM exceeding VCC or GND are clamped by the internal diodes. Limit forward diode current to maximum current rating.

ANALOG SWITCH CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

				_	40°C to +85°	С	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
R _{ON}	ON Resistance (Note 2)	$V_{CC} = 3.0 \text{ V}$ $I_{COM} = 10 \text{ mA}$ $V_{NO} \text{ or } V_{NC} = V_{IH} \text{ or } V_{IL}$	3.0	-		4.5	Ω
		V_{CC} = 5.0 V I_{COM} = 10 mA V_{NO} or V_{NC} = V_{IH} or V_{IL}	5.0	-		3.5	
ΔR _{ON}	ON Resistance Match Between Channels (Note 2 and 3)	V_{CC} = 3.6 V I_{COM} = 10 mA V_{NO} or V_{NC} = V_{IH} or V_{IL}	3.6	-	0.1	0.4	Ω
		V_{CC} = 5.5 V I_{COM} = 10 mA V_{NO} or V_{NC} = V_{IH} or V_{IL}	5.5			CN	
R _{FLAT[ON]}	ON Resistance Flatness (Note 4)	$I_{COM} = 10 \text{ mA}$ $V_{IS} = 0 \text{ to } V_{CC}$	3.0		NOE	T.5	Ω
		I _{COM} = 10 mA V _{IS} = 0 to V _{CC}	5.5	RN		1.36	
INO_[OFF] INC_[OFF]	NO_, NC_ Off-Leakage Current (Note 5)	$V_{CC} = 3.6 \text{ V} \\ V_{COM} = 0.3 \text{ V or } 3.3 \text{ V} \\ V_{NO} \text{ or } V_{NC} = 0.3 \text{ V or } 3.3 \text{ V} \\ \end{cases}$	3.6	Onser	0.01	+1.0	nA
		$V_{CC} = 5.5 \text{ V}$ $V_{COM} = 0 \text{ V or } 5.0 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0 \text{ V or } 5.0 \text{ V}$	5.5	012/10	0.01	+1.0	
I _{COM_[ON]}	COM_ On-Leakage Current (Note 5)	$V_{CO} = 3.6 \text{ V}$ $V_{COM} = 0.3 \text{ V or } 3.3 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0.3 \text{ V or } 3.3 \text{ V}$	3.6	-2.0	0.01	+2.0	nA
	OLEIS	$V_{CC} = 5.5 \text{ V}$ $V_{CDM} = 0 \text{ V or } 5.0 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0 \text{ V or } 5.0 \text{ V}$	5.5	-2.0	0.01	+2.0	

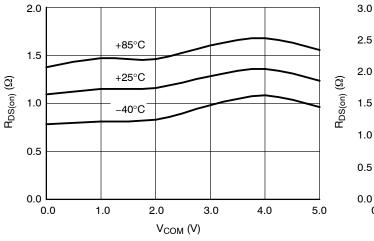
ANALOG SWITCH AC CHARACTERISTICS

	112, 56			-	40°C to +85°	C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{ON}	Turn-On Time	$V_{NC_}$, $V_{NO_} = V_{IH}$ or V_{IL} $R_L = 300 \ \Omega$, $C_L = 35 \ pF$ $V_{IN[x]} = V_{IH}$ or V_{IL}	1.8 to 5.5	-	-	30	nS
t _{OFF}	Turn-Off Time	$V_{NC_}$, $V_{NO_} = V_{IH}$ or V_{IL} $R_L = 300 \ \Omega$, $C_L = 35 \ pF$ $V_{IN[x]} = V_{IH}$ or V_{IL}	1.8 to 5.5	-	-	40	nS
^t BBM	Break-Before-Make Time Delay (Note 5)	$V_{NC_{-}}, V_{NO_{-}} = 1.5 \text{ V}$ $R_{L} = 300 \Omega, C_{L} = 35 \text{ pF}$	-	-	8.0	-	nS
t _{SKEW}	Skew (Note 5)	$R_S = 39 \Omega$, $C_L = 50 pF$	-	_	0.15	2.0	nS

- 2. R_{ON} characterized for V_{CC} range (1.65 V to 5.5 V). 3. $\Delta R_{ON} = R_{ON}(MAX) R_{ON}(MIN)$. 4. $R_{FLAT[ON]} = R_{ON}(MAX) R_{ON}(MIN)$, measured over V_{CC} range. 5. Guaranteed by design.

ANALOG SWITCH APPLICATION CHARACTERISTICS

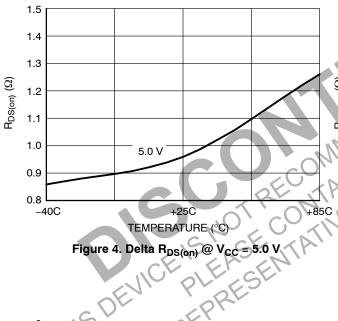
				-	-40°C to +85°	C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Uni
Q	Charge Injection	$V_{\text{IN}} = V_{\text{CC}}$ to GND $R_{\text{In}} = 0~\Omega,~C_{\text{L}} = 1.0~\text{nF}$ $Q = C_{\text{L}} - \Delta V_{\text{OUT}}$	3.0 5.0		6.0 9.0		рC
VISO	Off-Isolation	f = 10 MHz V _{NO} _, V _{NC} _ = 1.0 Vp-p R _L = 50 Ω, C _L = 5.0 pF	1.65 to 5.5		-50		dB
		$f = 1.0 \text{ MHz} \\ V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p} \\ R_L = 50 \ \Omega, \ C_L = 5.0 \text{ pF} \\ \end{cases}$			-75		
VCT	Cross-Talk	$f = 10 \text{ MHz}$ $V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p}$ $R_L = 50 \ \Omega, \ C_L = 5.0 \text{ pF}$	1.65 to 5.5		-80	,GN	dB
		$f = 1.0 \text{ MHz} \\ V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p} \\ R_L = 50 \ \Omega, \ C_L = 5.0 \text{ pF} \\$			-110 N D	510	
BW	On-Channel -3.0 db Bandwidth	Signal = 0 dB $R_L = 50 \Omega$, $C_L = 5.0 pF$	1.8 to 5.0	ORN	40		MHz
THD	Total Harmonic Distortion	$V_{COM} = 2.0 \text{ Vp-p},$ RL = 600 Ω , T _A = 25°C	-0	FO'se'	0.02	4	%
C _{NO_[OFF]} C _{NC_[OFF]}	NO_, NC_ OFF-Capacitance	F = 10 MHz	NOFIE	ON	30		pF
C _{NO_[ON]}	NO_, NC_ ON-Capacitance	F = 10 MHz	10%	KO,	110		pF
	AIS DEVICE PLANTS	RECONTACTOR OF THE PRESENTATIVE	FOR				



2.0 1.5 +85°C +25°C 1.0 -40°C 0.5 0.0 1.0 0.0 0.5 1.5 2.0 2.5 3.0 V_{COM} (V)

Figure 2. Low $R_{DS(on)}$ @ V_{CC} = 5.0 V

Figure 3. Low $R_{DS(on)} @ V_{CC} = 3.0 V$



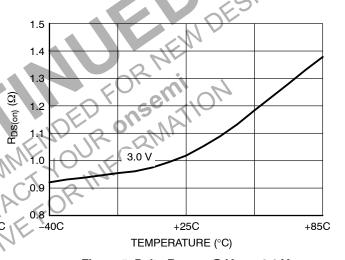
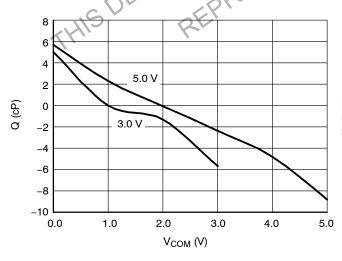


Figure 5. Delta R_{DS(on)} @ V_{CC} = 3.0 V



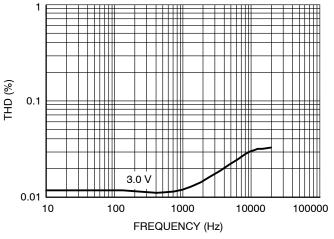
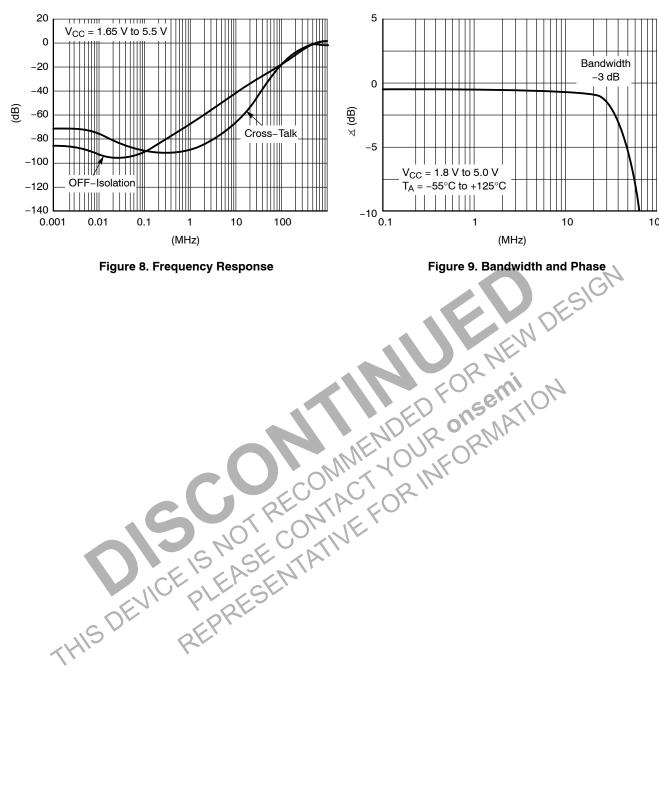
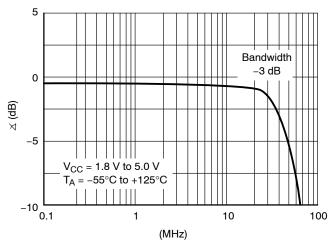


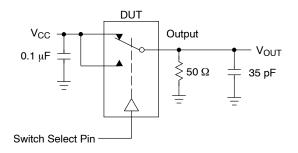
Figure 6. Charge Injection

Figure 7. Total Harmonic Distortion









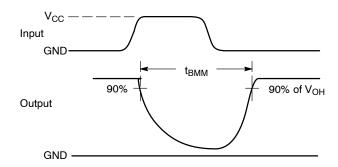


Figure 10. t_{BBM} (Time Break-Before-Make)

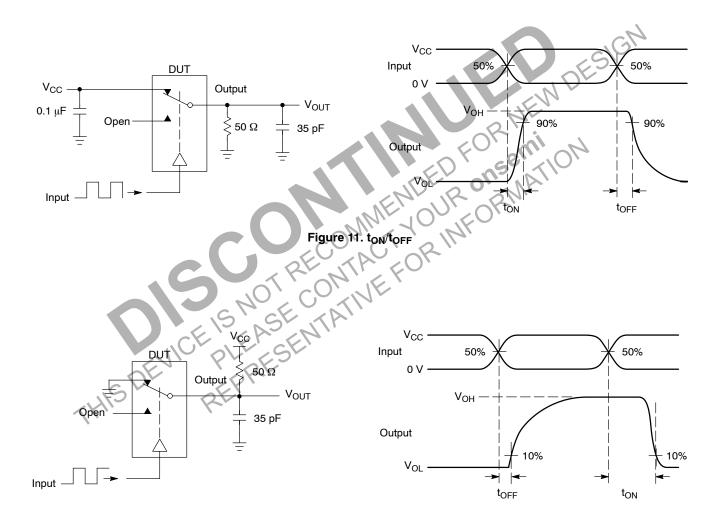
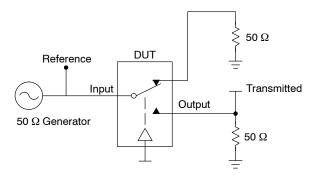


Figure 12. t_{ON}/t_{OFF}



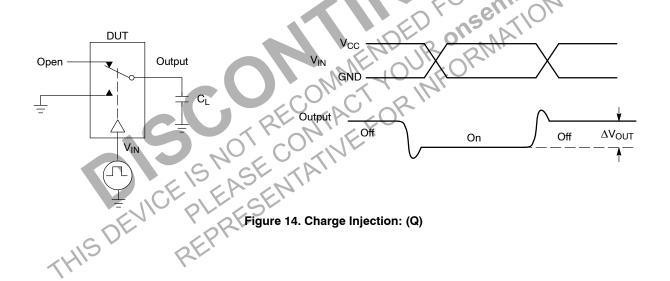
Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. VISO, Bandwidth and VONL are independent of the input signal direction.

$$\begin{split} &V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log}\bigg(\frac{V_{OUT}}{V_{IN}}\bigg) \text{ for } V_{IN} \text{ at } 100 \text{ kHz} \\ &V_{ONL} = \text{On Channel Loss} = 20 \text{ Log}\left(\frac{V_{OUT}}{V_{IN}}\right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz} \end{split}$$

Bandwidth (BW) = the frequency 3.0 dB below V_{ONL}

 V_{CT} = Use V_{ISO} setup and test to all other switch analog input/outputs terminated with 50 Ω

Figure 13. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V_{ONL}



DATE 04 MAY 2004



10 PIN FLIP-CHIP CASE 489AA **ISSUE A**



SCALE 4:1

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION:
- MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS				
DIM	MIN	MIN MAX			
Α		0.650			
A1	0.210 0.270				
A2	0.280 0.380				
D	1.965 BSC				
Е	1.465	BSC			
b	0.250	0.350			
е	0.500 BSC				
D1	1.500 BSC				
E1	1.000	BSC			

GENERIC MARKING DIAGRAM*



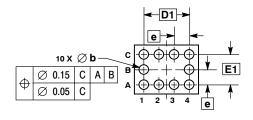
= Specific Device Code XXXX

YY = Year WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

4 X	← D → A B
○ 0.10 C	
PIN ONE CORNER	E V

		-A1	
// 0.10 C		+	
<u> </u>	A2 ¥	Α	
○ 0.075 C	7	Ť	C SEATING PLANE



DOCUMENT NUMBER:	98AON12946D	P8AON12946D Electronic versions are uncontrolled except when accessed directly from the Printed versions are uncontrolled except when stamped "CONTROLLED CO		
DESCRIPTION:	10 PIN FLIP-CHIP		PAGE 1 OF 1	

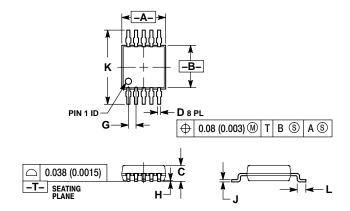
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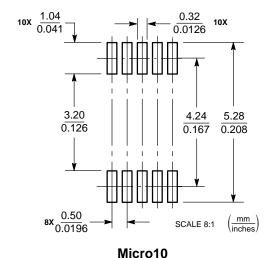


Micro10 CASE 846B ISSUE D

DATE 07 DEC 2004



SOLDERING FOOTPRINT



NOTES:

- DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION "B" DOES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION
- SHALL NOT EXCEED 0.25 (0.010) PER SIDE. 846B-01 OBSOLETE. NEW STANDARD
- 846B-02

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.95	1.10	0.037	0.043	
D	0.20	0.30	0.008	0.012	
G	0.50	0.50 BSC		0.020 BSC	
Н	0.05	0.15	0.002	0.006	
J	0.10	0.21	0.004	0.008	
K	4.75	5.05	0.187	0.199	
L	0.40	0.70	0.016	0.028	

GENERIC MARKING DIAGRAM*



XXXX = Device Code = Assembly Location Α

Υ = Year W = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	Micro10		PAGE 1 OF 1	

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